

The RF Line

NPN SILICON HIGH FREQUENCY TRANSISTOR

... designed for high voltage and high current f_T switching applications. These devices are also ideal for CRT drivers.

- High Collector-Emitter Breakdown Voltage —
 $V_{(BR)CEO} = 100 \text{ Vdc (Min) (at } I_C = 10 \text{ mA)}$
- High Current-Gain — Bandwidth Product —
 $f_T = 800 \text{ MHz (Typ) (at } I_C = 50 \text{ mA)}$
- Characterized with Safe Operating Area (SOA) Curves

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CEO}	100	Vdc
Collector-Base Voltage	V_{CBO}	100	Vdc
Emitter-Base Voltage	V_{EBO}	3.5	Vdc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	2.5 14	Watts mW/ $^\circ\text{C}$
Storage Temperature Range	T_{stg}	-65 to +200	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	71	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

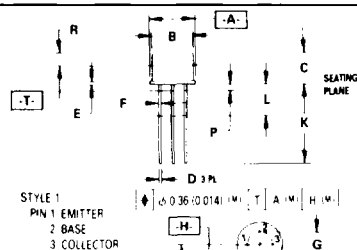
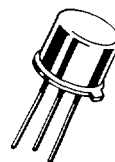
Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Breakdown Voltage ($I_C = 10 \text{ mA}, I_B = 0$)	$V_{(BR)CEO}$	100			Vdc
Collector-Base Breakdown Voltage ($I_C = 0.1 \text{ mA}, I_E = 0$)	$V_{(BR)CBO}$	100			Vdc
Emitter-Base Breakdown Voltage ($I_E = 0.1 \text{ mA}, I_C = 0$)	$V_{(BR)EBO}$	3.5			Vdc
Collector Cutoff Current ($V_{CE} = 75 \text{ Vdc}, V_{BE} = 0$)	I_{CES}			10	μA
ON CHARACTERISTICS					
DC Current Gain ($I_C = 50 \text{ mA}, V_{CE} = 10 \text{ Vdc}$)	h_{FE}	25			
Collector-Emitter Saturation Voltage ($I_C = 10 \text{ mA}, I_B = 1.0 \text{ mA}$)	$V_{CE(sat)}$			1.0	Vdc

DYNAMIC CHARACTERISTICS

Current-Gain — Bandwidth Product ($I_C = 50 \text{ mA}, V_{CE} = 25 \text{ Vdc}, f = 100 \text{ MHz}$)	f_T	500	800		MHz
Output Capacitance ($V_{CB} = 10 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz}$)	C_{ob}			4.0	pF
Input Capacitance ($V_{BE} = 3.0 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz}$)	C_{ib}		9.0		pF

MRF531

**HIGH FREQUENCY
TRANSISTOR**
NPN SILICON



NOTES

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION J MEASURED FROM DIMENSION A MAXIMUM.
4. DIMENSION B SHALL NOT VARY MORE THAN 0.025 (0.010) IN ZONE R. THIS ZONE CONTROLLED FOR AUTOMATIC HANDLING.
5. DIMENSION F APPLIES BETWEEN DIMENSION P AND L. DIMENSION D APPLIES BETWEEN DIMENSION L AND K. MINIMUM LEAD DIAMETER IS UNCONTROLLED IN DIMENSION P AND BEYOND DIMENSION K MINIMUM.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.51	9.39	0.335	0.370
B	7.75	8.50	0.305	0.335
C	6.10	6.60	0.240	0.260
D	0.41	0.53	0.016	0.021
E	0.23	1.04	0.009	0.041
F	0.41	0.48	0.016	0.019
G	5.08 BSC		0.200 BSC	
H	0.72	0.86	0.028	0.034
J	0.74	1.14	0.029	0.045
K	12.70	19.05	0.500	0.750
L	6.35	—	0.250	—
M	45 BSC		45 BSC	
P	—	1.27	—	0.050
R	2.54	—	0.100	—

**CASE 79-04
TO-205AD
(TO-39)**

FIGURE 1 – CURRENT-GAIN – BANDWIDTH PRODUCT

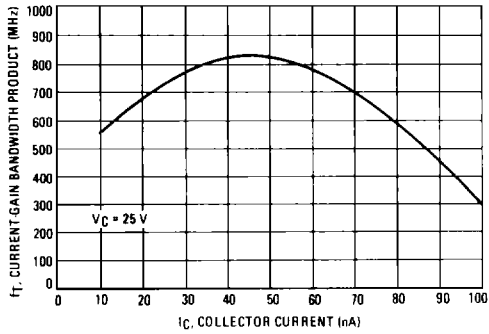


FIGURE 2 – INPUT CAPACITANCE

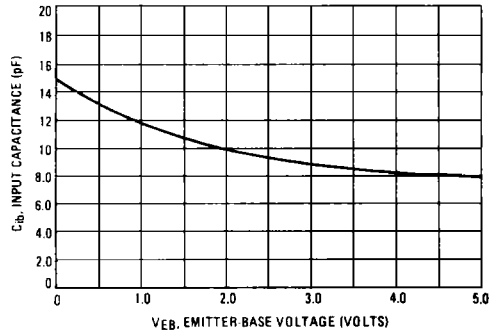


FIGURE 3 – OUTPUT CAPACITANCE

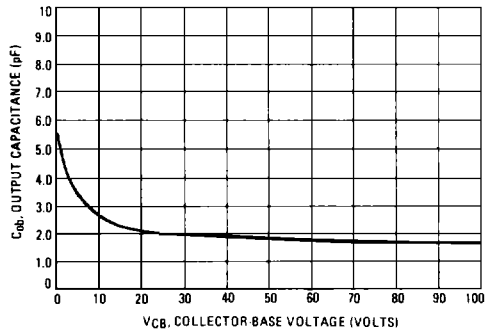


FIGURE 4 – DC SAFE OPERATING AREA

